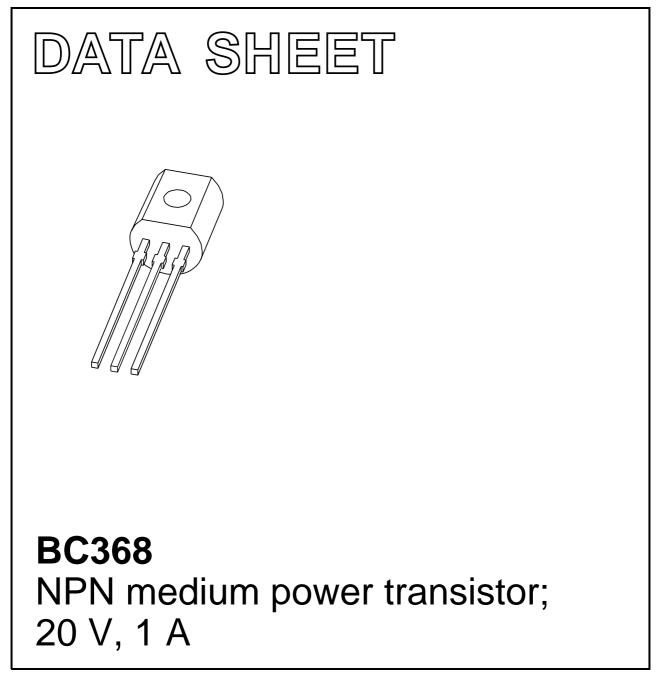
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2003 Dec 01 2004 Nov 05



FEATURES

• High current.

APPLICATIONS

- Linear voltage regulators
- Low side switch
- Supply line switch for negative voltages
- MOSFET driver
- Audio (pre-) amplifier.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	_	20	V
I _C	collector current (DC)	-	1	А
I _{CM}	peak collector current	-	2	А
h _{FE}	DC current gain	85	375	-

DESCRIPTION

NPN medium power transistor (see "Simplified outline, symbol and pinning" for package details).

PRODUCT OVERVIEW

TYPE NUMBER	P/	ACKAGE	MARKING CODE	PNP COMPLEMENT	
	PHILIPS	EIAJ	MARKING CODE		
BC368	SOT54	SC-43A	C368	BC369	

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER		PINNING		
	TYPE NUMBER SIMPLIFIED OUTLINE AND SYMBOL		DESCRIPTION	
BC368		1	base	
		2	collector	
		3	emitter	

ORDERING INFORMATION

TYPE NUMBER		PACKAGE			
	NAME	NAME DESCRIPTION VERSION			
BC368	SC-43A	plastic single-ended (through hole) package; 3 leads SOT			

BC368

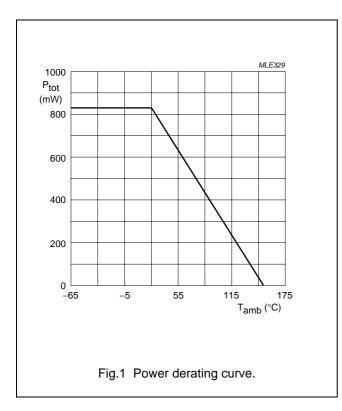
LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	32	V
V _{CEO}	collector-emitter voltage	open base	_	20	V
V _{EBO}	emitter-base voltage	open collector	_	5	V
I _C	output current (DC)		_	1	mA
I _{CM}	peak collector current		_	2	mA
I _{BM}	peak collector current		_	200	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; notes 1 and 2	_	0.83	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	+150	°C

Notes

- 1. Refer to SOT54 (SC-43A) standard mounting conditions.
- 2. Device mounted on an FR4 printed-circuit board, single-sided copper, tin-plated footprint.



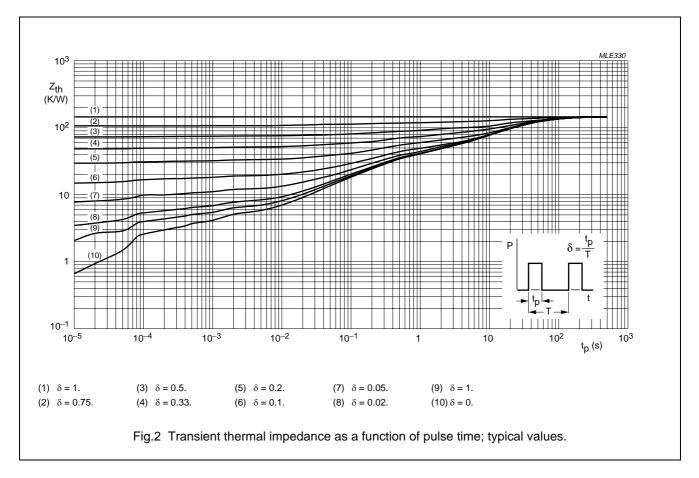
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	T_{amb} \leq 25 °C; notes 1 and 2	150	K/W

Notes

1. Refer to SOT54 (SC-43A) standard mounting conditions.

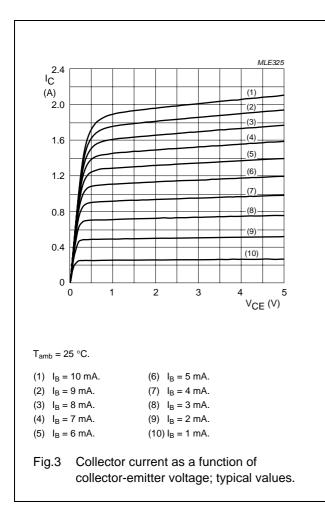
2. Device mounted on an FR4 printed-circuit board, single-sided copper, tin-plated footprint.

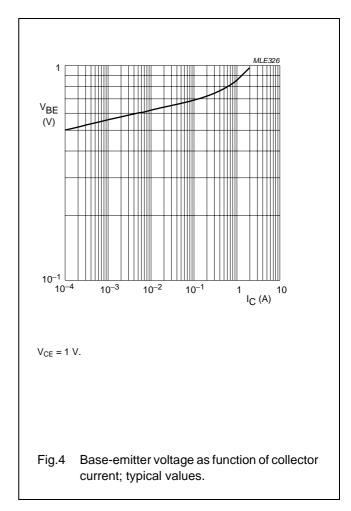


CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

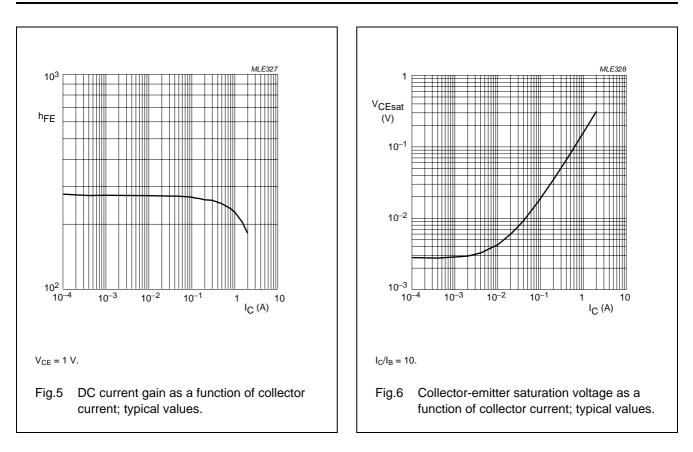
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	V _{CB} = 25 V; I _E = 0 A	-	-	100	nA
		$V_{CB} = 25 \text{ V}; I_E = 0 \text{ A};$ $T_{amb} = 150 \text{ °C}$	-	-	10	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 V; I_{C} = 0 A$	-	-	100	nA
h _{FE}	DC current gain	$V_{CE} = 10 \text{ V}; \text{ I}_{C} = 5 \text{ mA}$	50	_	_	
		$V_{CE} = 1 \text{ V}; I_{C} = 500 \text{ mA}$	85	-	375	
		$V_{CE} = 1 \text{ V}; \text{ I}_{C} = 1 \text{ mA}$	60	-	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 1 A; I _B = 100 mA	-	-	500	mV
V _{BE}	base-emitter voltage	V _{CE} = 10 V; I _C = 5 mA	-	-	700	mV
		V _{CE} = 1 V; I _C = 1 A	-	-	1	V
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = i_e = 0 \text{ A};$ f = 1 MHz	-	22	-	pF
f _T	transition frequency	$V_{CE} = 5 \text{ V}; I_{C} = 50 \text{ mA};$ f = 100 MHz	40	170	-	MHz



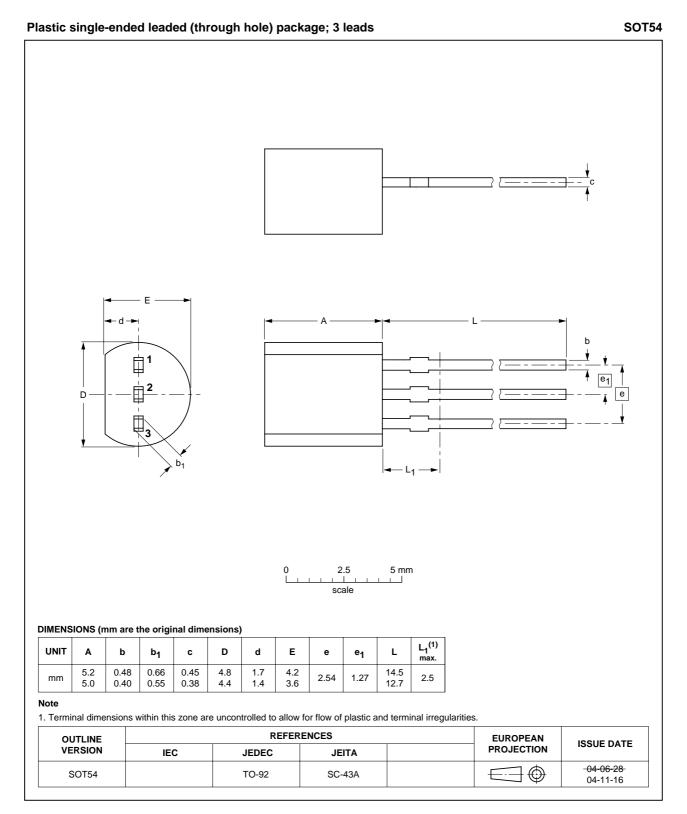


BC368

NPN medium power transistor; 20 V, 1 A



PACKAGE OUTLINE



DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
- The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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